Wideband Quad 2:1 Video **Switch**

The NCS6433 is a wide bandwidth, bidirectional, Quad 2:1, NMOS-based video switch suitable for dealing with video signals such as RGB, composite, S-Video, and component video (YPbPr).

The NCS6433 is controlled by a single switch–enabled (\overline{OE}) input. When \overline{OE} is low the switch is enabled and the A port is connected to the B port. When \overline{OE} is high the switch is disabled and the high-impedance state exists between the A and B ports. The line select (SEL) input controls the data path of the multiplexer/demultiplexer.

The NCS6433 has a wide bandwidth, low crosstalk, low on resistance, and fast switching times making it suitable for high-frequency video applications in high definition LCD TV's.

Features

- Very Wide Frequency Bandwidth: 570 MHz
- Low Switch Serial Resistance R_{DS(on)}, 4 Ω Typical
- Power Supply Voltage, 5 V
- Less Than 0.25 ns Bidirectional Maximum Propagation Delay Through Switch
- Low Quiescent Current: 3 μA Maximum
- Very Low Crosstalk, -80 dB Typical at 10 MHz
- Control Inputs are TTL/CMOS Compatible
- Ideal for High Definition Video Applications
- ESD HBM Protection 8 kV
- Fast Switching Better Than 10 ns
- Capable of Driving a High Current at the Output (>100 mA)
- Available in SOIC-16 or TSSOP-16 Package
- This is a Pb-Free Device

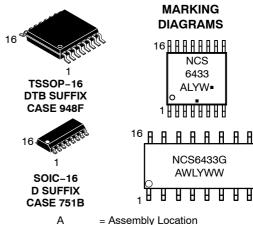
Typical Applications

- Flat Panel Displays including LCDTV
- CRT Displays
- DVD Reader/Writer
- Set-Top Boxes



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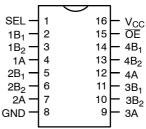


= Wafer Lot WL, L Υ = Year

WW. W = Work Week G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

PIN CONNECTIONS



TRUTH TABLE

SEL	ŌĒ	Function
X	H	Open
L	L	A = B ₁
H	L	A = B ₂

PIN NAMES

1

Pin	Description
ŌĒ	Bus Switch Enables
SEL	Select Inputs
A	Bus A
B ₁ , B ₂	Bus B

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

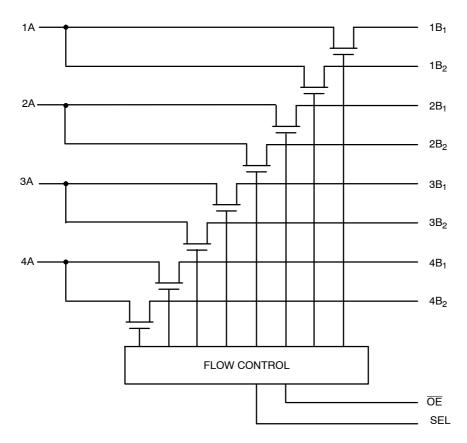


Figure 1. NCS6433 Block Diagram

ORDERING INFORMATION

Device Order Number	Package	Shipping [†]
NCS6433DR2G	SOIC-16 (Pb-Free)	2500 / Tape & Reel
NCS6433DTBR2G	TSSOP-16 (Pb-Free)	2500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ATTRIBUTES

Characteristics	Value						
ESD Protection Human Body Model, R = 1000 Ω , C = 100 pl (Note 1) Machine Model	F I/O Pins 2–7, 9–14 All Pins All Pins	8 kV 2 kV 100 V					
Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in.					
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latch-up Test							

- 1. Meets or exceeds JEDEC spec JESD22-A114-B.
- 2. For additional information, see Application Note AND8003/D

MAXIMUM RATINGS

Parameter		Symbol	Value	Unit
DC Supply Voltage		V _{CC}	-0.5 to +5.5	V
DC Input Voltage		VI	-0.5 to +5.5	V
DC Output Voltage		Vo	-0.5 to +5.5	V
DC Input Diode Current		I _{IK}	-50	mA
DC Output Diode Current		I _{OK}	-50	mA
DC Output Sink Current		Ιο	128	mA
DC Supply Current per Supply Pin		I _{CC}	±100	mA
DC Ground Current per Ground Pin		I_{GND}	±100	mA
Storage Temperature Range		T _{STG}	−65 to +150	°C
Lead Temperature, 1 mm from Case for 10 Seconds		TL	260	°C
Junction Temperature Under Bias (Note 3)		T_J	+150	°C
Thermal Resistance	SOIC-16 TSSOP-16	θ_{JA}	125 170	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

RECOMMENDED OPERATING CONDITIONS

Symbol	Par	Min	Max	Unit	
V _{CC}	Supply Voltage	Operating, Data Retention Only	4.75	5.25	V
VI	Input Voltage	(Note 4)	0	5.25	V
Vo	Output Voltage	(HIGH or LOW State)	0	5.25	V
T _A	Operating Free-Air Temperature		-40	+85	°C
Δt/ΔV	Input Transition Rise or Fall Rate Switch I/O	Switch Control Input V_{CC} = 5.0 V \pm 0.5 V	0	DC 5	ns/V

^{4.} Unused control inputs may not be left open. All control inputs must be tied to a high or low logic input voltage level.

^{3.} Maximum electrical ratings are defined as those values beyond which damage to the device may occur at $T_A = +25$ °C.

DC ELECTRICAL CHARACTERISTICS ($T_A = -40^{\circ}C$ to $+85^{\circ}C$ for Min and Max values, $T_A = 25^{\circ}C$ for Typ values)

Symbol	Parameter	Conditions	V _{CC} (V)	Min	Тур*	Max	Unit
V _{IK}	Clamp Diode Voltage	I _{IN} = -18 mA	4.5	-1.2	-0.8		V
V _{IH}	High-Level Input Voltage		4.0 to 5.5	2.0			V
V _{IL}	Low-Level Input Voltage		4.0 to 5.5			0.8	V
ILI	Input Leakage Current	$0 \le V_{IN} \le 5.5 \text{ V}$	5.5			±1.0	μΑ
l _{OZ}	Off-State Leakage Current	$0 \le A, B \le V_{CC}$	5.5			±1.0	μΑ
R _{ON}	Switch On Resistance (Note 5)	V_{IN} = 1 V, I_{ON} = 13 mA, R_L = 75 Ω	4.5		4.0	7.0	Ω
		V_{IN} = 2 V, I_{ON} = 26 mA, R_L = 75 Ω	4.5		7.0	10	
I _{CC}	Quiescent Supply Current	V _{IN} = V _{CC} or GND, I _{OUT} = 0	5.5			3.0	μΑ
Δl _{CC}	Increase In I _{CC} per Input	One input at 3.4 V, Other inputs at V _{CC} or GND	5.5			2.5	mA

AC ELECTRICAL CHARACTERISTICS ($T_A = -40$ °C to +85 °C, $C_L = 20$ pF, RU = RD = 75 Ω unless otherwise specified) (Note 6)

			V _{CC} = 4.5–5.5 V			
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
t _{ON}	Turn On Time	R_L = 75 Ω , C_L = 20 pF, see Figure 7		2.8	5.0	ns
t _{OFF}	Turn Off Time	R_L = 75 Ω , C_L = 20 pF, see Figure 7		1.4	5.0	ns
BW	−3 dB Bandwidth	R _L = 150 Ω, T _A = 25°C			570	MHz
X _{talk}	Crosstalk Adjacent Non-Adjacent	10 MHz, $C_L = 0$ pF, $R_L = 150 \Omega$		-47 -80		dB
Off _{ISO}	Off Isolation	10 MHz, C_L = 0 pF, R_L = 150 Ω		-48		dB

^{6.} $T_A = +25^{\circ}C$, parameters characterized but not tested.

CAPACITANCES (Note 7)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
C _{IN}	Control Pin Input Capacitance	V _{CC} = 5.0 V		2.0		pF
C _{I/OA}	A Port Input/Output Capacitance	$V_{CC} = \overline{OE} = 5.0 \text{ V}$		5.0		pF
C _{I/OB}	B Port Input/Output Capacitance	$V_{CC} = \overline{OE} = 5.0 \text{ V}$		5.0		pF

^{7.} $T_A = +25^{\circ}C$, f = 1 MHz, Capacitance is characterized but not tested.

^{*}Typical values are at V_{CC} = 5.0 V and T_A = 25°C.

5. Measured by the voltage drop between A and B pins at the indicated current through the switch. On resistance is determined by the lower of the voltages on the two (A or B) pins.

TYPICAL CHARACTERISTICS

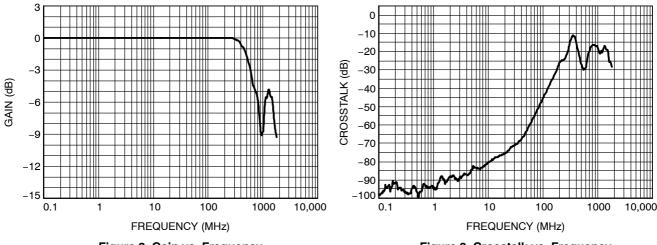


Figure 2. Gain vs. Frequency

Figure 3. Crosstalk vs. Frequency (Non-Adjacent Channels)

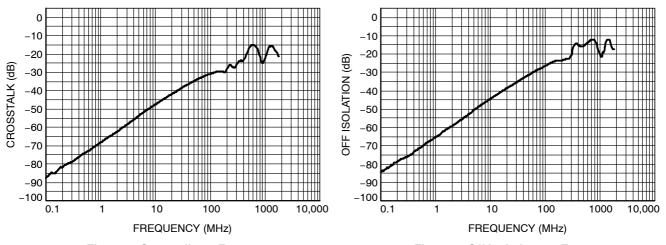


Figure 4. Crosstalk vs. Frequency (Adjacent Channels)

Figure 5. Off Isolation vs. Frequency

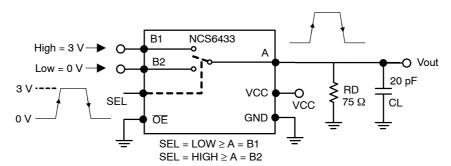


Figure 6. AC Test Circuit for Turn-on and Turn-off Times

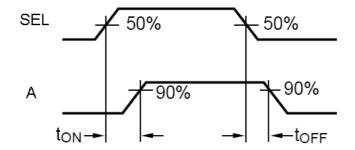


Figure 7. Turn-on and Turn-off Times

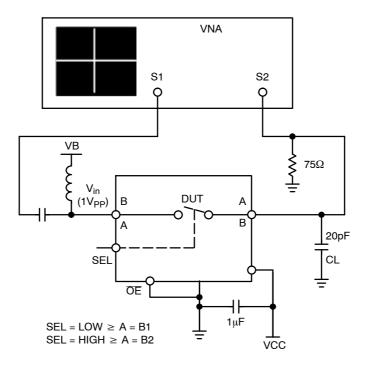


Figure 8. Gain, Crosstalk, Off-Isolation

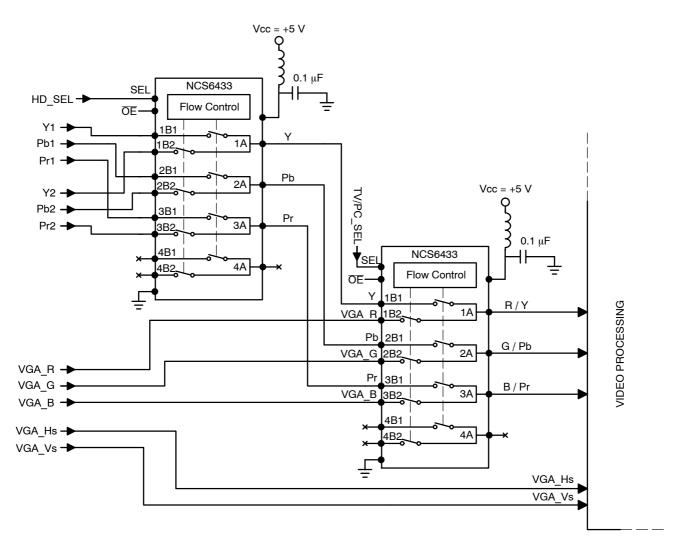


Figure 9. Example of LCDTV Application Using the Video Switch NCS6433

MECHANICAL CASE OUTLINE



DATE 29 DEC 2006

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI
- THE NOTION AND TOLETANOING FER ANSI'Y 14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
 DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
- PHOI HUSION.

 MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.

 DIMENSION D DOES NOT INCLUDE DAMBAR
 PROTRUSION. ALLOWABLE DAMBAR PROTRUSION

 SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D

 DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	METERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	9.80	10.00	0.386	0.393
В	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	BSC	0.050	BSC
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

STYLE 1:		STYLE 2:		STYLE 3:		STYLE 4:			
PIN 1.	COLLECTOR	PIN 1.	CATHODE	PIN 1.	COLLECTOR, DYE #1	PIN 1.	COLLECTOR, DYE	#1	
2.	BASE	2.	ANODE	2.	BASE, #1	2.	COLLECTOR, #1		
3.	EMITTER	3.	NO CONNECTION	3.	EMITTER, #1	3.	COLLECTOR, #2		
4.	NO CONNECTION	4.	CATHODE	4.	COLLECTOR, #1	4.	COLLECTOR, #2		
5.	EMITTER	5.	CATHODE	5.	COLLECTOR, #2	5.	COLLECTOR, #3		
6.	BASE	6.	NO CONNECTION		BASE, #2	6.	COLLECTOR, #3		
7.	COLLECTOR	7.	ANODE	7.		7.	COLLECTOR, #4		
8.	COLLECTOR	8.	CATHODE	8.	COLLECTOR, #2	8.	COLLECTOR, #4		
9.	BASE	9.	CATHODE	9.	COLLECTOR, #3	9.	BASE, #4		
10.	EMITTER	10.	ANODE	10.	BASE, #3	10.	EMITTER, #4		
11.	NO CONNECTION	11.	NO CONNECTION	11.	EMITTER, #3	11.	BASE, #3		
12.	EMITTER	12.	CATHODE	12.	COLLECTOR, #3	12.	EMITTER, #3		
13.	BASE	13.	CATHODE	13.	COLLECTOR, #4	13.	BASE, #2	OOL DEDING	COOTDONT
14.	COLLECTOR	14.	NO CONNECTION	14.	BASE, #4	14.	EMITTER, #2	SOLDERING	FOOTPRINT
15.	EMITTER	15.	ANODE	15.	EMITTER, #4	15.	BASE, #1		8X
16.	COLLECTOR	16.	CATHODE	16.	COLLECTOR, #4	16.	EMITTER, #1		i.40 — →
								- 0	.40
STYLE 5:		STYLE 6:		STYLE 7:					16X 1.12
PIN 1.	DRAIN, DYE #1		CATHODE	PIN 1.	SOURCE N-CH				10% 1.12
2.	DRAIN, #1		CATHODE	2.	COMMON DRAIN (OUTPU	Τ\		1	16
3.	DRAIN, #2	3.		3.	COMMON DRAIN (OUTPU			, L .	'0
3. 4.	DRAIN, #2	3. 4.	CATHODE	3. 4.	GATE P-CH	1)		- —	
4. 5.	DRAIN, #2	4. 5.	CATHODE	4. 5.	COMMON DRAIN (OUTPU	Τ\		, , , , , , , , , , , , , , , , , , , 	
5. 6.	DRAIN, #3	6.	CATHODE	6.	COMMON DRAIN (OUTPU		16	5X 1 -	
7.	DRAIN, #4	7.	CATHODE	7.	COMMON DRAIN (OUTPU		0.5	58	, L
8.	DRAIN, #4	8.	CATHODE	8.	SOURCE P-CH	•,			
9.	GATE, #4	9.	ANODE	9.	SOURCE P-CH				
10.	SOURCE, #4	10.	ANODE	10.	COMMON DRAIN (OUTPU	T)			
11.	GATE, #3	11.		11.	COMMON DRAIN (OUTPU				
12.	SOURCE, #3	12.		12.	COMMON DRAIN (OUTPU				
13.	GATE, #2	13.		13.	GATE N-CH	.,			
14.	SOURCE, #2	14.		14.	COMMON DRAIN (OUTPU	T)			V PITCH
15.	GATE, #1	15.	ANODE	15.	COMMON DRAIN (OUTPU				1 <u>+=</u> 1- 1
16.	SOURCE, #1		ANODE	16.	SOURCE N-CH	.,			
								□ 8	9 + - + -
									~
									' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' '
									DIMENSIONS: MILLIMETERS

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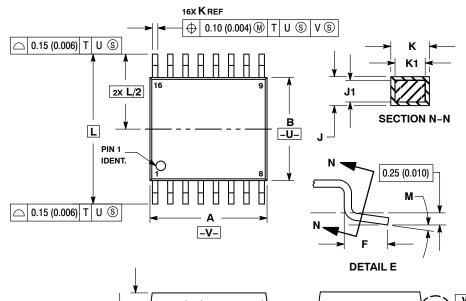
-T- SEATING PLANE





TSSOP-16 CASE 948F-01 ISSUE B

DATE 19 OCT 2006



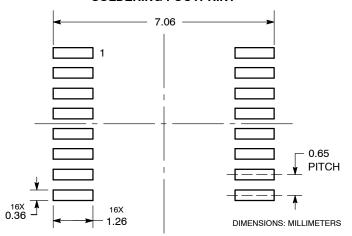
NOTES

- JIES:
 DIMENSIONING AND TOLERANCING PER
 ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
 DIMENSION A DOES NOT INCLUDE MOLD
 FLASH. PROTRUSIONS OR GATE BURRS.
 MOLD EL ROLL OF GATE BURDS SUAL NO.
- MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION.
 INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
- DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION. TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.
- 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	4.90	5.10	0.193	0.200
В	4.30	4.50	0.169	0.177
C		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
Н	0.18	0.28	0.007	0.011
7	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
Ы	6.40 BSC		0.252 BSC	
М	0 °	8 °	0 °	8 °

SOLDERING FOOTPRINT

G



GENERIC MARKING DIAGRAM*

168888888 XXXX XXXX **ALYW** 188888888

XXXX = Specific Device Code Α = Assembly Location

= Wafer Lot L Υ = Year W = Work Week = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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